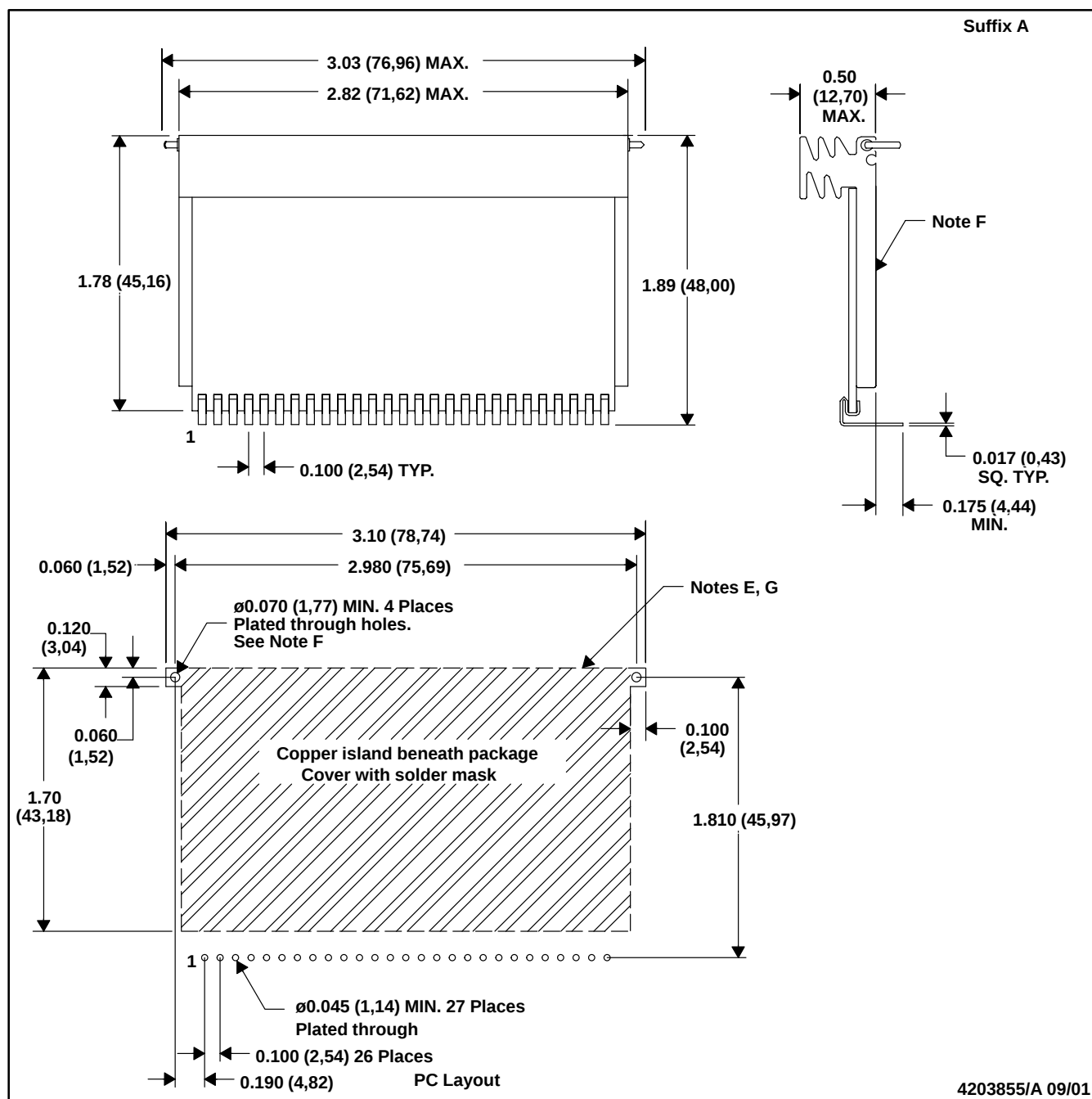


EJA (R-MSIP-T27)

METAL SINGLE-IN-LINE MODULE



- NOTES: A. All linear dimensions are in inches (mm).
B. This drawing is subject to change without notice.
C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
E. Recommended mechanical keep out area.

- F. The heatsink is isolated but electrically conductive. No signal traces are allowed under the heatsink area. A solid copper island is recommended, which may be connected to ground.
G. Case outline reference.

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